

#### N-Channel Enhancement Mode Power MOSFET

### **Description**

The RM5N150S8 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> = 150V,I<sub>D</sub> =4.6A

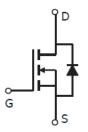
 $R_{DS(ON)} < 75 \text{m}\Omega \text{ @ } V_{GS} = 10 \text{V} \quad \text{(Typ:63m}\Omega\text{)}$ 

 $R_{DS(ON)}$  < 88m $\Omega$  @  $V_{GS}$ =4.5V (Typ:70m  $\Omega$ )

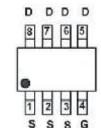
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current

### **Application**

- DC/DC Primary Side Switch
- Telecom/Server
- Synchronous Rectification
- Halogen-free



Schematic diagram



Marking and pin assignment



SOP-8 top view

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
5N150	RM5N150S8	SOP-8	Ø330mm	12mm	4000 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	150	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	4.6	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	2.9	А
Pulsed Drain Current	I <sub>DM</sub>	35	А
Maximum Power Dissipation	P <sub>D</sub>	3.1	W
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 150	°C

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	40	°C/W

## Electrical Characteristics (T<sub>A</sub>=25 <sup>°</sup>C unless otherwise noted)

### **Static Characteristics**

Devementar	Cymbal	Conditions		Value		
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	150	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	1	2	3	\ \ \ \
Zero Gate Voltage Drain Current		V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>j</sub> =25°C	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>j</sub> =100°C	-	-	100	μΑ
Gate to Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Drain to Source on Resistance	Б	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	-	63	75	
Drain to Source on Resistance	$R_{DS(on)}$	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	-	70	88	mΩ
Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =5A	-	18	-	S
Gate Resistance	$R_{G}$	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHz	-	5.0	-	Ω

## **Dynamic Characteristics**

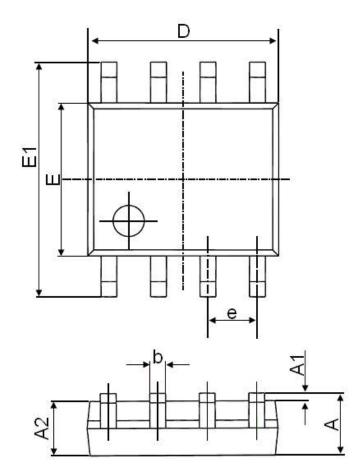
Input Capacitance	C <sub>iss</sub>		-	625	-	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =75V, f=1MHz	-	37	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	-	-	13	-	
Total Gate Charge (10V)	Q <sub>g</sub> (10V)		-	11.6	-	
Total Gate Charge (4.5V)	Q <sub>g</sub> (4.5V)	V <sub>DD</sub> =75V, I <sub>D</sub> =5A, V <sub>GS</sub> =10V		6.5		-0
Gate to Source Charge	$Q_{gs}$	- V <sub>DD</sub> -75V, I <sub>D</sub> -5A, V <sub>GS</sub> -10V	-	1.2	-	nC
Gate to Drain (Miller) Charge	$Q_{gd}$		-	4	-	
Turn on Delay Time	$t_{d(on)}$		-	10	-	
Rise time	t <sub>r</sub>	$V_{DD}$ =75V, $I_{D}$ =5A, $V_{GS}$ =10V,	-	7	-	ne
Turn off Delay Time	$t_{d(off)}$	$R_G=10\Omega$ ,	-	14	-	ns
Fall Time	t <sub>f</sub>		-	3	-	

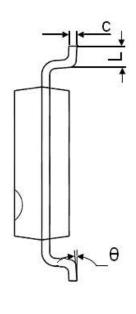
### **Reverse Diode Characteristics**

Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =5A	-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	IT		50	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	V <sub>R</sub> =75V, I <sub>F</sub> =5A, dI <sub>F</sub> /dt=100A/μs	-	70	-	nC



# **SOP-8 Package Information**





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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